

IQS128 / IQS128L Datasheet IQ Switch® - ProxSense® Series

Single Channel Capacitive Proximity/Touch Controller

The IQS128 / IQS128L ProxSense[®] IC is a fully integrated capacitive sensor implementing Dynamic Calibration (DYCAL™) technology: intelligent hysteresis to allow for sensor drift even during sensor activation.

aariiig	concor donvation.	_	
Featur	res		IQS128 TSOT23-6
	DYCAL™: Intelligent Hysteresis	L	
	Internal Capacitor Implementation (ICI) – reference capacitor on-chip		23 ₈₄
	Automatic Tuning Implementation (ATI) -	S128L DFN8 (2x3)	
	Automatic adjustment for optimal sensor performance		
	Supply voltage: 2.95V to 5.5V		
	Minimum external components		DAME
	1-Wire open drain data streaming option	IQSYNOTE THAT	RoHS
	Advanced on-chip digital signal processing		compliant
	User selectable (OTP):		
	External synchronisation control or		
	External control over filter operation		
	I/O Sink or Source selection		
	Time-out for stuck key		
	Proximity and Touch sensitivity selections		
	IQS128L: Low Power options available		

Keys:	Touch:	5mm x 5mm or larger (overlay thickness dependent)		
	Proximity:	Various electrical options (wire / PCB trace / ITO / conductive foil)		
Dielectric:	Material:	Various non-metal materials (i.e. glass, plastic, painted surfaces)		
	Thickness:	6 mm plastic, 10 mm glass for touch. Very thick overlay possible for proximity		

Applications Occupancy sensors SAR qualification for Tablet PC's On-ear detection for mobile phones SD glasses Personal Media Players White goods and appliances	Human Interface Devices Proximity activated backlighting Any applications where a touch and proximity condition can prevail for an extended period of time with or without a host controller
Advantages Allows for sensor drift in periods of activation and non-activation Improved digital filtering to reduce external noise	Minimal power consumption ($<7\mu A$) when in standby mode (Charge Halt).

Available Options

T _A	TSOT23-6	DFN8 (2x3)
-40°C to 85°C	IQS128	IQS128L





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1 Overview

1.1 Device variations

		Functionality								
Device	Package	DYCAL		LP	RF Noise	Pulse on	DYCAL	ATI	Touch	
		Release Threshold	Filter operation	Block ATI	modes	Detection	CTRL (Input)	Output	Base	Debounce
IQS128	TSOT23-6	75%	Normal	-	-	Available	Reseed	TOUT	4 values	3
IQS128L	DFN8(2x3)	75% & 87.5%	Updated	3sec after exiting TM	4 Power Modes	-	Re-ATI	POUT or TOUT	8 values	2

Please note: Except for the functional variations stated above, there also exist differences between the proximity and touch thresholds for the IQS128L version. More on this in Sections 6.4 & 6.5.

1.2 Device

The IQS128 and IQS128L ICs will be referred to as IQS128/IQS128L throughout the datasheet, unless they have different functionality, where it will be explicitly stated and explained.

The IQS128/IQS128L is a single channel capacitive proximity and touch device which employs an internal voltage regulator and reference capacitor (Cs).

The IQS128/IQS128L device has a dedicated pin for the connection of a sense electrode (Cx) and output pin for proximity and touch events on OUT. The polarity of the output pins can be configured. A 1-wire open drain data streaming protocol is implemented for debugging purposes.

Special device configuration can be done by setting one time programmable (OTP) options.

The device automatically tracks slow varying environmental changes via various signal processing algorithms and has an Automatic Tuning Implementation (ATI) algorithm to calibrate the device to the sense electrode.

DYCAL™ (Dynamic Calibration) is a special form of hysteresis that can track slow varying environmental change even while the sensor is in a touch state.

The *charge transfer* method of capacitive sensing is employed on the IQS128/IQS128L. (The charge transfer principle is thoroughly described in the application note: "AZD004 - Azoteq Capacitive Sensing".)

1.3 Operation

The device has been designed to be used in applications where proximity is required and touch conditions can prevail for an extended period of time which may result in uncompensated drift in conventional capacitive sensors.

A low threshold is used to detect the proximity of an object, with a higher threshold for touch detection.

Dynamic Calibration is performed when a TOUCH condition is detected for longer than T_{DYNACAL} . The hysteresis algorithm will now check for the release condition of the touch, while still tracking environmental changes

1.4 Applicability

All specifications, except where specifically mentioned otherwise, provided by this datasheet are applicable to the following ranges:

Temperature:	100 to	. 050
i elliberature.	-4 00 เบ	+000

□ Supply voltage (V_{DDHI}): 2.95V to 5.5V





2 Pin-Out

The IQS128 is available in a TSOT23-6 package and the IQS128L is available in a DFN8(2x3) package.

2.1 IQS128

2.1.1 Pin-out

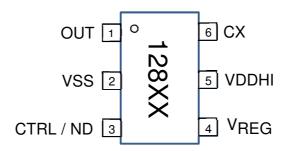
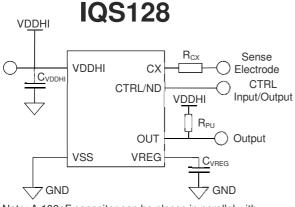


Figure 2.1 Pin-out of IQS128 package

Table 2.1 Pin-out description

	IQS128				
Pin Name Type Function		Function			
1	OUT	Digital Out	Output		
2	VSS	Ground	GND Reference		
3	CTRL / ND	Digital Input/Output	Control input or proximity output / ND pin		
4	VREG	Analogue Output	Internal Regulator Pin (Connect 1µF bypass capacitor)		
5	VDDHI	Supply Input	Supply Voltage Input		
6	CX	Analogue	Sense Electrode		

2.1.2 Schematic



Note: A 100pF capacitor can be places in parallel with the existing capacitors between VDDHI and GND as well as between VREG and GND for added RF immunity.

Figure 2.2 Typical application schematic of IQS128

2.1.3 Typical values

Component	Value
C _{VREG}	1uF
R _{CX}	470 Ω (typical)
R _{PU} *	4.7 kΩ (typical)
C _{VDDHI}	1uF

^{*} R_{PU} is only needed if device is setup in active Low state.





2.2 IQS128L

2.2.1 **Pin-out**

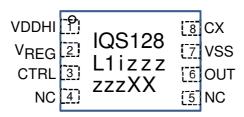
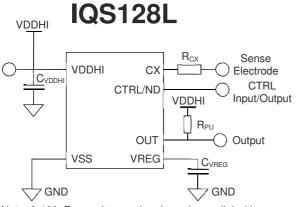


Figure 2.3 Pin-out of IQS128L package

Table 2.2 Pin-out description

	IQS128L					
Pin Name Type Function		Function				
1	VDDHI	Supply Input	Supply Voltage Input			
2	VREG	Analogue Output	Internal Regulator Pin (Connect 1µF bypass capacitor)			
3	CTRL	Digital Input/Output	Control input or proximity output			
4	NC	-	No Connect			
5	NC	-	No Connect			
6	OUT	Digital Out	Output			
7	VSS	Ground	GND Reference			
8	CX	Analogue	Sense Electrode			

2.2.2 Schematic



Note: A 100pF capacitor can be places in parallel with the existing capacitors between VDDHI and GND as well as between VREG and GND for added RF immunity.

Figure 2.4 Typical application schematic of IQS128L

2.2.1 Typical values

Component	Value
C _{VREG}	1uF
R _{CX}	470 Ω (typical)
R _{PU}	4.7 kΩ (typical)
C _{VDDHI}	1uF

^{*} R_{PU} is only needed if device is setup in active Low state.





3 User Configurable Options

Table 4.1 and Table 4.2 list the user configurable settings.

The device is fully functional in its default state, but some applications may require alternative configuration settings. These settings are enabled by configuring One Time Programmable (OTP) user options.

Configuration can be done on packaged devices or in-circuit. In-circuit configuration may be limited by values of external components chosen.

Popular configurations are available exstock — please check with the local distributor for availability. Azoteq can supply pre-configured devices for large quantities.

3.1 Configuring Devices

Azoteg offers a Configuration Tool (CTxxx) accompanying software that can (USBProg.exe) be used program the OTP user options More prototyping purposes. regarding the configuration of the device with the USBProg program is explained by application note: "AZD007 - USBProg Overview" which can be found on the Azotea website.

Alternative programming solutions for the IQS128/IQS128L also exist. For further enquiries regarding this, please contact Azoteq at ProxSenseSupport@azoteq.com or the local distributor.

-Section 6.5

3.1.1 IQS128 User Selectable Options

bit 7-5

Table 3-1: IQS128 Bank 0 User Selectable Options

T_{THR}<2:0>: Touch Thresholds (counts)

Bit	7	6	5	4	3	2	1	0
Name	T _{THR2}	T _{THR1}	T_{THR0}	P _{THR1}	P _{THR0}	ND	LOGIC	EXT_CTRL
Default	0	0	0	0	0	0	0	0

000 = 16001 = 40010 = 60011 = 90100 = 130101 = 200110 = 340111 = 500-Section 0 bit 4-3 P_{THB}<1:0>: Proximity Thresholds (counts) 00 = 401 = 810 = 1211 = 16 ND: RF Noise Detection -Section 6.3.1 hit 2 0 - Disable RF Noise Detect 1 = Enable RF Noise Detect **LOGIC:** Output logic select (Only when STREAMING mode is disabled) -Section 6.7 hit 1 0 = ¹Software Open Drain Active Low 1 = Active High -Section 6.1 bit 0 EXT CTRL: Selects external control option on OUT 0 = Charge Halt 1 = Halt LTA filter

¹ Only applicable for OUT pin. If CTRL is configured as output, it is a push-pull output.





Table 3-2: IQS128 Bank 1 User Sel	ectable Options
-----------------------------------	-----------------

Bit	7	6	5	4	3	2	1	0
Name	STREAMING	~	~	T_{HALT1}	T _{HALT0}	~	~	CTRL_DIRECTION
Default	0	0	0	0	0	0	0	0

bit 7 STREAMING: 1-wire streaming protocol -Section 0

0 = Disabled 1 = Enabled

bit 6-5 Unimplemented

bit 4-3 T_{THALT}<1:0>: Filter Halt Settings -Section 6.7

00 = Always 01 = 18s 10 = 60s 11 = 3s

bit 2-1 Unimplemented

bit 0 CTRL_DIRECTION: Configures Control pin as input or output

0 = Input for external control from MCU (used with Bank0-bit 0) -Section 0

1 = Output Mode Operation

Table 3-3: IQS128 Bank 2 User Selectable Options

Bit	7	6	5	4	3	2	1	0
Name	~	~	~	~	~	ATI _{BASE1}	ATI _{BASE0}	~
Default	~	~	~	~	~	0	0	~

bit 7-4 Unimplemented

bit 2-1 ATI_{BASE}<1:0>: Base value selections -Section 8.1

00 = 200 counts 01 = 100 counts 10 = 150 counts 11 = 250 counts

bit 0 Unimplemented





3.1.2 IQS128L User Selectable Options

Table 3-4: IQS128L Bank 0 User Selectable Options

Bit	7	6	5	4	3	2	1	0
Name	T _{THR2}	T _{THR1}	T _{THR0}	P _{THR1}	P _{THR0}	ND	LOGIC	EXT_CTRL
Default	0	0	0	0	0	0	0	0

bit 7-5 T_{THR}<2:0>: Touch Thresholds (counts) -Section 6.5 000 = 40001 = 60010 = 100011 = 200 100 = 360101 = 500110 = 700111 = 900-Section 0 bit 4-3 P_{THR}<1:0>: Proximity Thresholds (counts) 00 = 401 = 810 = 16 11 = 32bit 2 Unimplemented **LOGIC:** Output logic select (Only when STREAMING mode is disabled) -Section 6.7 bit 1 0 = ²Software Open Drain Active Low 1 = Active High bit 0 **EXT_CTRL:** Selects external control option on OUT -Section 6.1 0 = Charge Halt 1 = Halt LTA filter

² Only applicable for OUT pin. If CTRL is configured as output, it is a push-pull output.





Table 3-5:	IQS128L	Bank 1 User Selectable Options
	. ~	

Bit	7	6	5	4	3	2	1	0
Name	STREAMING	LP1	LP0	T_{HALT1}	T _{HALT0}	~	~	CTRL_DIRECTION
Default	0	0	0	0	0	0	0	0

bit 7 STREAMING: 1-wire streaming protocol -Section 0

0 = Disabled

1 = Enabled

bit 6-5 LP<1:0>: Low Power Mode timings -Section 6.8

00 = 9.01ms (Boost Power Mode) 01 = 27ms (Normal Power Mode) 10 = 100ms (Low Power Mode 1) 11 = 300ms (Low Power Mode 2)

bit 4-3 T_{THALT}<1:0>: Filter Halt Settings -Section 6.7

00 = Always 01 = 18s 10 = 60s 11 = 3s

bit 2-1 Unimplemented

bit 0 CTRL_DIRECTION: Configures Control pin as input or output

0 = Input for external control from MCU (used with Bank0-bit 0) -Section 0

1 = Output Mode Operation

Table 3-6: IQS128L Bank 2 User Selectable Options

Bit	7	6	5	4	3	2	1	0
Name	~	~	DYCAL_OUTPUT	RELEASE_THRES	ATI _{BASE2}	ATI _{BASE1}	ATI _{BASE0}	۲
Default	~	7	0		0	0	0	٧

bit 7-6 Unimplemented

Bit5 DYCAL_OUTPUT: OUT pin will react with the detection of a -Section 9.2

0 = Proximity 1 = Touch

bit4 RELEASE_THRES: Release Threshold - DYCAL (% of Touch Threshold) -Section 9.1

0 = 75%1 = 87.5%

bit 3-1 ATI_{BASE}<3:0>: Base value selections -Section 8.1

000 = 200 counts 001 = 250 counts 010 = 300 counts 011 = 350 counts 100 = 400 counts 101 = 550 counts 110 = 700 counts 111 = 850 counts

bit 0 Unimplemented





4 Measuring capacitance using the *Charge Transfer* method

The *charge transfer* method of capacitive sensing is employed on the IQS128/IQS128L. (The charge transfer principle is thoroughly described in the application note: "AZD004 - Azoteq Capacitive Sensing".)

A charge cycle is used to take a measurement of the capacitance of the sense electrode (connected to Cx) relative to ground. It consists of a series of pulses charging Cx and discharging Cx to the reference capacitor, at the charge transfer frequency (FCX - refer to Section 10). The number of the pulses required to reach a trip voltage on the reference capacitor is referred counts (CS) which instantaneous capacitive measurement. The CS value is used to determine if either a physical contact or a proximity event has occurred based on the change in CS detected. The typical values of CS, without a touch or a proximity condition range between 1344 and 1865, although higher and lower CS can be used based on the application

requirements. With CS larger than +/-1865 the gain of the system may become too high causing unsteady CS.

The IQS128/IQS128L schedules a charge cycle every t_{SAMPLE} seconds to ensure regular samples for processing of results. The duration of the charge cycle is defined as t_{CHARGE} and varies according to the CS required to reach the trip voltage. Other activities, such as data streaming (if device is in streaming mode), are completed between charge cycles.

Please note: Attaching a probe to the Cx pin will increase the capacitance of the electrode and therefore the CS. This may have an immediate influence on the CS (decrease t_{CHARGE} - thus CS) and cause a proximity or a touch event. After t_{HALT} seconds the system will adjust accommodate for this change. If the total load on Cx, with the probe attached is still lower than the maximum Cx load the system will continue to function normally after tHALT seconds the probe with attached.

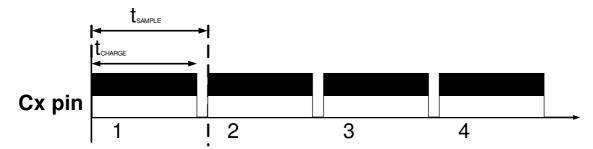


Figure 4.1 Charge cycles as can be see on CX

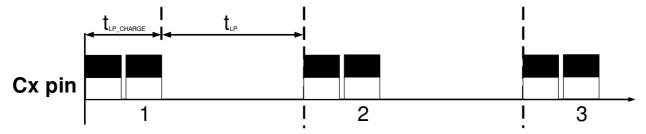


Figure 4.2 Charge cycles as charged in LP modes (IQS128L only)





5 DYCALTM

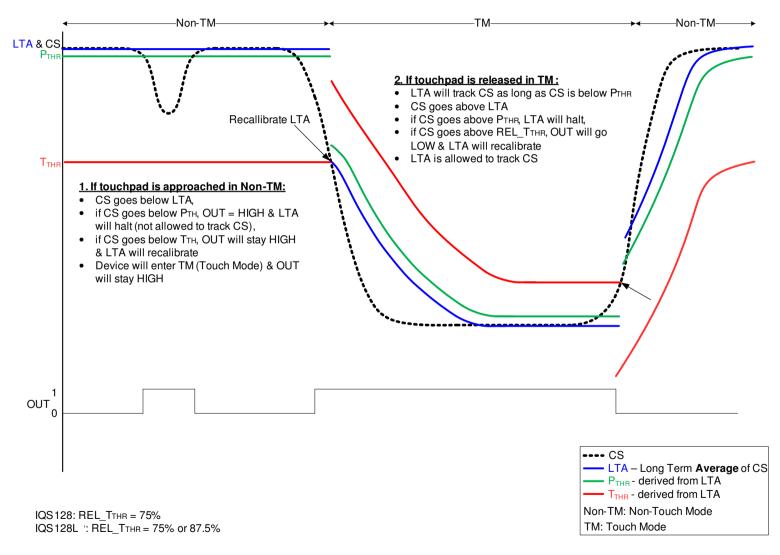


Figure 5.1 DYCAL Operation







5.1 Operating Principle

Figure 5.1 is a visual representation of the DYCAL functionality. The OUT pin is used to indicate the status of a DYCAL event (both a proximity and a touch event). The DYCAL functionality is summarised below.

5.2 Non-Touch Mode

The OUT pin is activated on the successful detection of a proximity event and will remain activated for the duration of the proximity event, permitting that this event is not longer than the filter halt timings. The LTA will be halted in this time.

As soon as a touch condition is detected (CS below T_{THR}), the controller will dynamically re-calibrate its LTA to the halted LTA – T_{THR} . The IC is now in Touch Mode.

5.3 Touch Mode

After the re-calibration of the LTA, it will follow the CS and be allowed to track slow varying environmental changes. If the CS were to exceed the LTA by a release threshold (REL $_{THR}$) the touch detection will stop and the OUT pin will return to its original state.





6 Configurable Settings

This section describes the user configurable options of the IQS128/IQS128L in more detail.

User programmable options are selected by configuring the OTP selections. Please refer to section 3 for an overview of the configurable settings.

6.1 EXT_CTRL: External Control

The user has the option to control some parameters of the IQS128/IQS128L from an external source. The IC can be used in default mode (CTRL unconnected) or the user can use the CTRL pin to select whether the master should halt the charge transfers (i.e. stop operation) or to halt LTA filter tracking on the IQS128/IQS128L.

6.1.1 Charge Halt

If CTRL is sampled high for longer than $T_{\text{EXT_HALT}}$, the charge conversion cycle will be halted, once the current conversion has been completed. The device will remain in this standby mode until the CTRL line is sampled low again. An automatic reseed is performed directly after CTRL is released to compensate for any environmental changes which might have occurred during the standby mode.

6.1.2 Halt LTA filter

When configured in this mode, CTRL can be used to control the LTA halt times when sampled high. The CTRL pin has precedence over the configurations bits selected for the halt timings.

If CTRL is sampled high for longer than $T_{\text{EXT_HALT}}$, the filter will be halted until this pin is sampled low.

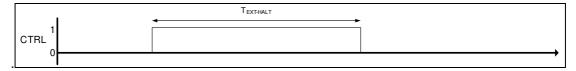


Figure 6.1 Master Output signal on CTRL pin to Halt Operation or Filter Halt

6.1.3 Pulse on CTRL:

The pulse on the CTRL pin needs to adhere to the following timing constraints:

 $25ms < T_{PULSE} < 35ms$

6.1.3.1 **IQS128: Reseed**

A reseed condition can be initiated by generating a pulse on the CTRL pin. The LTA will be reset to the CS, forcing the OUT pin to its original state.

If the CS value is outside its allowable limits, the device will force an ATI event to reset the system sensitivity. (Please refer to section 8 for more detail).

6.1.3.2 **IQS128L: re-ATI**

A re-ATI condition can be initiated by generating a pulse on the CTRL pin. This function can be issued at any time.

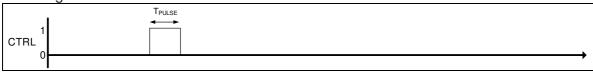


Figure 6.2 Master Output signal on CTRL to force a Reseed Condition





6.2 LOGIC

The logic used by the device can be selected as active HIGH or active LOW. The output pins OUT and CTRL will function based on this selection.

Configuration: Bank0 bit1: Logic Output Selection

Bit	Selection
0	Software Open Drain Active Low
0	Active High

A software open drain output is implemented for the OUT pin when configured in active low mode. The voltage on the pull-up resistor is limited to the IQS128/IQS128L supply voltage. A $4k7-10k\Omega$ resistor between OUT and VDDHI is recommended.

6.3 RF Noise on IQS128/IQS128L

6.3.1 ND: RF Noise Detection (IQS128)

The IQS128 has RF Noise Detect (ND) functionality. (This option is not available on the IQS128L.) If ND function is enabled, the IQS128 is able to detect RF Noise on the CTRL / ND pin. Further details on the working of this can be found in the Application Notes: AZD015 and AZD015b.

6.3.2 IQS128/IQS128L RF Noise Immunity

The IQS128/IQS128L has advanced immunity to RF noise sources such as GSM cellular telephones, DECT, Bluetooth and WIFI devices. Design guidelines should however be followed to ensure the best noise immunity. The design of capacitive sensing applications can encompass a large range of situations but as a summary the following should be noted to improve a design:

- A ground plane should be placed under the IC, except under the Cx line.
- All the tracks on the PCB must be kept as short as possible.
- The capacitor between VDDHI and VSS as well as between VREG and VSS, must be placed as close as possible to the IC.
- A 100 pF capacitor should be placed in parallel with the 1uF capacitor

between VDDHI and VSS. Another 100 pF capacitor can be placed in parallel with the 1uF capacitor between VREF and VSS.

- If the device is too sensitive for a specific application a parasitic capacitor (max 5pF) can be added between the Cx line and ground.
- Proper sense electrode and button design principles must be followed.
- Unintentional coupling of sense electrode to ground and other circuitry must be limited by increasing the distance to these sources.
- In some instances a ground plane some distance from the device and sense electrode may provide significant shielding from undesired interference.

When the capacitance between the sense electrode and ground becomes too large the sensitivity of the device may be influenced.

6.4 P_{THR[1:0]} Proximity Threshold

The IQS128/IQS128L has 4 proximity threshold settings indicated in CS. The proximity threshold is selected by the designer to obtain the desired sensitivity and noise immunity. A proximity event is triggered if the CS diverges more than the selected count from the LTA for 6 consecutive cycles.

IQS128

Configuration: Bank0 bit 4-3
PTH:PTHO:Proximity Thresholds

- 100100	100	Cannot I I I Control						
Bit	Sele	Selection						
00	4	(Most sensitive)						
01	8							
10	12							
11	16	(Least sensitive)						

IQS128L

Configuration: Bank0 bit 4-3
PTHR::PTHRO::Proximity Thresholds

Bit	Sele	Selection					
00	4	(Most sensitive)					
01	8						
10	16						
11	32	(Least sensitive)					





6.5 T_{THR[2:0]}Touch Threshold

The IQS128/IQS128L has 8 touch threshold settings indicated in CS. The touch threshold is selected by the designer to obtain the desired touch sensitivity. A touch event is triggered if the CS diverges more than the selected count from the LTA for 2 consecutive cycles.

In the NO-TOUCH state the CS must diverge more than the touch threshold value <u>below</u> the LTA. Operating in the TOUCH STATE, the CS must diverge more than REL_T_{THR} of the touch threshold value <u>above</u> the LTA

The following equation is used to determine if a touch or release event occurred.

NO TOUCH STATE: LTA – CS \leftarrow T_{THR} TOUCH STATE: CS - LTA \rightarrow REL_T_{THR}

IQS128

Configuration: Bank0 bit 7-5 T_{THR2}:T_{THR0} Touch Thresholds

Bit	Sele	ction
000	16	(Most sensitive)
001	40	
010	60	
011	90	
100	130	
101	200	
110	340	
111	500	(Least sensitive)

IQS128L

Configuration: Bank0 bit 7-5 T_{THR2}:T_{THR0} Touch Thresholds

1000	104011 11110011010					
Bit	Bit Selection					
000	40	(Most sensitive)				
001	60					
010	100					
011	200					
100	360					
101	500					
110	700					
111	900	(Least sensitive)				

6.6 CTRL DIRECTION

The CTRL pin can be configured as an input (default) or as an output. If configured as input, the IC has an internal pull-up resistor enabled. See Section 6.1 for more information on functionality of CTRL as input.

If the CTRL pin is configured as an output it, cannot be used to control the filter or charge transfer operation.

The CTRL pin is activated upon the successful detection of a proximity condition. The pin will remain activated for the duration of the proximity detection as indicated in figure 7.3. If a proximity condition is detected in conjunction with a touch event, the pin will only be deactivated when the touch condition is no longer detected as indicated in figure below.



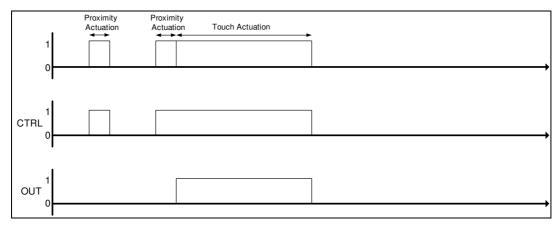


Figure 6.3 Proximity and Touch output

6.7 T_{HALT[1:0]} Filter Halt

The LTA filter only executes while no proximity events are detected to ensure compensation only for environmental changes. Once a touch event is detected the filter will resume operation and will on longer be halted. The halt timing configuration settings determine how long the filter is halted.

Configuration: Bank1 bit 4-3 T_{HALT1}:T_{HALT0} LTA Halt timings for proximity events

		90				
Bit	Sele	Selection				
00	ALW	AYS				
01	18	seconds				
10	60	seconds				
11	3	seconds				

The presence of a proximity condition for a time exceeding the halt time will be deemed as a fault state which would trigger a reseed event where after the output state on the OUT pin will be reset to its original condition.

6.8 LP_[1:0] Low Power Modes (IQS128L)

There exist 4 LP modes. The LP modes will decrease the sampling frequency of CS which will reduce the power consumption of the device. However, this will also increase the response time of the device.

Configuration: Bank1 bit 6-5 LP₁:LP₀ Low Power Modes

_		
I	Bit	Selection
	00	9.1ms (Boost Power Mode)
l	01	100ms (Normal Power Mode)
l	10	200ms (Low Power Mode 1)
	11	300ms (Low Power Mode 2)





7 Streaming Mode

For a more complete description of the data streaming protocol, please refer to Application Note AZD017 on the Azoteq website.

The IQS128/IQS128L has the capability to stream data to a MCU. This provides the designer the ability to obtain the parameters and sensor data within the device in order to aid design into applications. Data streaming is performed as a 1-wire data protocol on the OUT pin. The output function of this pin is therefore lost when the device is configured in streaming mode. Data Streaming can be enabled as indicated below:

Configuration: Bank1 bit7: Streaming Mode

Rit	Bit Selection						
DIL	Selection						
0	Disabled						
1	Enabled						

Figure 7.1 illustrates the communication protocol for initialising and sending data with the 1 wire communication protocol.

- Communications initiated by a START bit. Bit defined as a low condition for T_{START}.
- Following the START bit, is a synchronisation byte (T_{INIT} = 0xAA). This byte is used by the MCU for clock synchronisation.
- 3. Following T_{INIT} the data bytes will be sent. With short data streaming mode enabled, 5 bytes of data will be sent, otherwise 8 bytes will be sent after each charge cycle.
- Each byte sent will be preceded by a START bit and a STOP bit will follow every byte.
- 5. STOP bit indicated by taking pin 1 high. The STOP bit does not have a defined period.



Figure 7.1 Debug: 1-wire streaming Debug Mode

The following table defines the bit definitions for the IQS128/IQS128L devices during Streaming Mode.





Byte Definitions for Streaming Mode

Byte	Bit	Value
0	7:0	CS High byte
1	15:8	CS Low byte
2	23:16	LTA High byte
3	31:24	LTA Low byte
4	39	ATI busy
	38	Proximity Event Detected
	37	Touch Event Dectected
	36	OUT State Indication
	35	Not Used
	34	Zoom active
	33	Not Used
	32	Not Used
5	47	ATI Multiplier (I)
	46	ATI Multiplier (S)
	45	ATI Multiplier (S)
	44	Compensation (P4)
	43	Compensation (P3)
	42	Compensation (P2)
	41	Compensation (P1)
	40	Compensation (P0)
6	55:54	Not Used
	53	Compensation (P5)
	52	Touch Threshold Bit 2
	51	Touch Threshold Bit 1
	50	Touch Threshold Bit 0
	49	Proximity Threshold Bit 1
	48	Proximity Threshold Bit 0
7	63:56	Counter

Azoteq provides a <u>GUI</u> (Graphical User Interface) application that can be utilised to capture and visualise the data streamed from the IQS128/IQS128L.

8 Automatic Tuning Implementation (ATI)

ATI is a sophisticated technology implemented in the latest generation ProxSense® devices that optimises the performance of the sensor in a wide range of applications and environmental conditions (refer to application note AZD0027 - Automatic Tuning Implementation).

ATI makes adjustments through external reference capacitors unnecessary (as required by most other solutions) to obtain optimum performance.

8.1 ATI

The IQS128/IQS128L implements an ATI algorithm. This algorithm adjusts the ATI parameters to optimise the sensing electrode's connection to the device.

The device will execute the ATI algorithm whenever the device starts-up and or when the CS are not within a predetermined range.

There are 2 important definitions to understand for ATI:

8.1.1 ATI Target

ATI adjusts internal circuitry according to two parameters, the **ATI multiplier** and the **ATI compensation**.

- The ATI multiplier can be viewed as a course adjustment of CS, used to achieve the ATI BASE value.
- The ATI compensation is a fine adjustment used to reach the ATI TARGET value.

With these two parameters the CS of the IQS128/IQS128L is tuned until an ATI target value of 1600 is achieved.

8.1.2 ATI_{BASE}: Significance of ATI Base

As mentioned above, the **ATI multiplier** is used to select a base value for the ATI. The ATI BASE value is important, as this determines the sensitivity of the device. The sensitivity can be defined as:

Sensitivity = ATI TARGET / ATI BASE

The ATI Target remains fixed at 1600 and it can thus be seen from this that a larger base value will result in a less sensitive device. The designer has the option to increase/reduce the sensitivity of the system through the ATI BASE value. For most applications the ATI BASE should be kept default.



П



The options for the ATI BASE is as follows:

IQS128

Configuration: Bank2 bit 2-1
ATI_{BASE1}:ATI_{BASE0} ATI BASE values

Bit	Selection			
00	200 (Most sensitive)			
01	100			
10	150			
11	250 (Least sensitive)			

IQS128L

Configuration: Bank2 bit 3-1 ATI_{BASE2}:ATI_{BASE0} ATI BASE values

Bit	Selec	Selection				
000	200	(Most sensitive)				
001	250					
010	300					
011	350					
100	400					
101	550					
110	700					
111	850	(Least sensitive)				

8.2 Sensitivity due to ATI

The adjustment of the ATI parameters will result in variations in the CS and sensitivity. Sensitivity can be observed as the change in CS as the result of a <u>fixed</u> change in sensed capacitance. The ATI parameters have been chosen to provide significant overlap. It may therefore be possible to select various combinations of ATI multiplier and ATI compensation settings to obtain the same CS. The sensitivity of the various options may however be different for the same CS.

8.3 ATI Procedure

While the ATI algorithm is in progress this condition will be indicated in the streaming data and proximity and touch events cannot be detected. The device will only briefly remain in this condition and it will be entered only when relatively large shifts in the CS has been detected.

The ATI function aims to maintain a constant CS, regardless of the capacitance of the sense electrode (within the maximum range of the device).

The effects of ATI on the application are the following:

Automatic adjustment of the device configuration and processing parameters for a wide range of PCB and application designs to maintain a optimal configuration for proximity and touch detection.

Automatic tuning of the sense electrode at start-up to optimise the sensitivity of the application.

Automatic re-tuning when the device detects changes in the sensing electrode's capacitance to accommodate a large range of changes in the environment of the application that influences the sensing electrode.

Re-tuning only occurs during device operation when a relatively large sensitivity reduction is detected. This is to ensure smooth operation of the device during operation.

Re-tuning may temporarily influences the normal functioning of the device, but in most instances the effect will be hardly noticeable.

Shortly after the completion of the retuning process the sensitivity of a Proximity detection may be reduced slightly for a few seconds as internal filters stabilises.

ATI can be implemented so effectively due to:

Excellent	system	signal	to	noise	ratio
(SNR).					

☐ Effective digital signal processing to remove AC and other noise.

☐ The very stable core of the devices.

The built-in capability to accommodate a large range of sensing electrode capacitances.





9 DYCAL Specific settings

9.1 REL_T_{THR}: Release Threshold (IQS128L)

The IQS128L has the option to increase the release threshold when in TM. This helps that small variations caused by moving a finger/hand on a touch pad will not cause the IC to exit TM, making the solution more robust. The options available are shown below:

Configuration: Bank2 bit4: REL T_{THR}

	3 · · · · 1 · · · · 1
Bit	Selection
0	75%
1	87.5%

9.2 DYCAL OUTPUT (IQS128L)

The IQS128L can be configured to activate the OUT pin with either a proximity event or a touch event.

Choosing a proximity event, will make the activation of OUT more sensitive.

Using a touch event to activate OUT will make the system less sensitive which is needed in some applications. The LTA will still halt with the detection of a proximity but will not have an influence on the OUT pin. The LTA will still re-calibrate once a touch condition is detected.

Configuration: Bank2 bit5:DYCAL OUTPUT

Bit	Selection
0	Proximity
1	Touch





10 Electrical Specifications

10.1 Absolute Maximum Specifications

Exceeding these maximum specifications may cause damage to the device.

Operating temperature -40 °C to 85 °C

Supply Voltage $(V_{DDHI} - V_{SS})^3$ 6.5V

Maximum pin voltage (OUT, CTRL) $V_{DDHI} + 0.5V$

Pin voltage (Cx) 2.5V

Minimum pin voltage (VDDHI, VREG, OUT, CTRL, Cx) V_{SS} - 0.5V Minimum power-on slope 100V/s

ESD protection (VDDHI, VREG, V_{SS}, OUT, CTRL, Cx) 4kV

10.2 General Characteristics (Measured at 25°C)

Standard IQS128/IQS128L devices are rated for supply voltages between 2.95V and 5.5V.

DESCRIPTION Conditions PARAMETER TYP MAX **UNIT** MIN Supply voltage 2.95 5.50 V_{DDHI} $2.95 \le V_{DDHI} \le 5.5$ Internal regulator output V 2.35 2.50 2.65 V_{REG} Boost Power operating current 77 $2.95 \le V_{DDHI} \le 5.5$ I_{IQS128 BP} μΑ Standby operating current⁴ $2.95 \le V_{DDHI} \le 5.5$ 7 μΑ ISTANDBY Normal Power operating current $2.95 \le V_{DDHI} \le 5.5$ 31 μΑ I_{IQS128 NP} Low power 1 operating current $2.95 \le V_{DDHI} \le 5.5$ 17 μΑ I_{IQS128L LP1} $2.95 \le V_{DDHI} \le 5.5$ Low power 2 operating current 10.5 uА I_{IQS128L LP2}

Table 10.1 IQS128/IQS128L General Operating Conditions

Table 10.2 Start-up and shut-down slope Characteristics

DESCRIPTION	IC	Conditions	PARAMETER	MIN	MAX	UNIT
POR	D/S	V _{DDHI} Slope ≥ 100V/s	POR	1.45	1.70	٧
BOD	D/S		BOD	1.30	1.40	V

 $^{^{\}rm 3}$ Maximum voltage applied for OTP programming and not intended for operation.

⁴ CTRL = Input and CTRL = HIGH (Charge halt).





10.3 Output Characteristics (Measured at 25 °C)

Table 10.3 OUT Characteristics

Symbol	Description	I _{SOURCE} (mA)	Conditions	MIN	TYP	MAX	UNIT
	Output High voltage	1	$V_{\text{DDHI}} = 5.5V$		TBD		
V_{OH}		1	$V_{DDHI} = 3.3V$		TBD		V
		1	$V_{DDHI} = 2.95V$		TBD		
Symbol	Description	I _{SINK} (mA)	Conditions	MIN	TYP	MAX	UNIT
	Outrant Lance	1	$V_{\text{DDHI}} = 5.5V$	0.30	TBD		
V_{OL}	Output Low voltage	1	$V_{\text{DDHI}} = 3.3V$	0.20	TBD		V
	voltage	1	$V_{DDHI} = 2.95V$	0.20	TBD		

10.4 Timing Characteristics

Table 10.4 Main Oscillator⁵

SYMBOL	DESCRIPTION		Conditions	MIN	TYP	MAX	UNIT
Fosc	IQS128/IQS128L Noscillator	Main	2.95 ≤ V _{DDHI} ≤ 5.5	0.9	1	1.1	MHz

Table 10.5 IQS128L Response Times

Power Mode	Conditions	DYCAL		
Power Mode		Min**	Max	Unit
Boost Power Mode ⁶	Detection	27.3	-	ms
DOOST FOMEL MODE	Release	27.3	ı	ms
Normal Power Mode ⁷	Detection	111	ı	ms
Normal Fower Wode	Release	123	-	ms
Low Power Mode 1	Detection	301	ı	ms
Low Fower Mode I	Release	313	-	ms
Low Power Mode 2	Detection	821	-	ms
LOW FOWEI MOde 2	Release	832	-	ms

^{**}Minimum time calculated as a user touching and exceeding the T_{THR} . Touch debounce is 2 and I/O is toggled after next charge transfer cycle, requiring 3 charge cycles for the minimum time of a decision to be made.

Release_{MIN} = $3 \times t_{LP_CHARGE} + 2 \times t_{LP(max)}$ (t_{LP_CHARGE} is dependent on counts) (counts is longer)

Maximum time = Dependent on speed at which user approaches electrode

⁵ All timings are derived from the main oscillator.

⁶ Minimum Detection and Release times = 3 x t_{CHARGE}

⁷ Detection_{MIN} = 3 x t_{LP_CHARGE} + 2 x $t_{LP(max)}$ (t_{LP_CHARGE} is dependent on counts) (counts is short)





Table 10.6 General Timing Characteristics for 2.95V ≤ V_{DDHI} ≤ 5.5V

SYMBOL	DESCRIPTION	Conditions	MIN	TYP	MAX	UNIT
t _{HIGH}	Output high minimum time		9			ms
t_{LOW}	Output low minimum time		9			ms
F _{CX}	Charge transfer frequency			250		kHz
t _{CHARGE}	Charge cycle duration	CS = 1600, fcx = 250kHz		6.4		ms
t _{SAMPLE}	Refer to section 4					ms
t _{BP}	Sampling period in BP	t _{CHARGE} - 2 ≤ t _{SAMPLE}		9		ms
t _{BP}	Sampling period in BP	t _{CHARGE} ≥ t _{SAMPLE}		t _{CHARGE} +2		ms
t _{LP_CHARGE}	Low Power Charging time			CS*(1/F _{CX})+t _{CHARGE}		
t _{NP}	Low Power Time between charges for LP1. Refer to section 4		18.9	27	35.1	ms
t _{LP1}	Low Power Time between charges for LP1. Refer to section 4		70	100	130	ms
t _{LP2}	Low Power Time between charges for LP1. Refer to section 4		210	300	390	ms
t _{START}	Refer to section 0		14.4	17	18.8	us
t _{INIT}	Refer to section 0			136		us
t _{DATA}	Refer to section 0			136		us
T _{DYNACAL}	Dynamic Calibration time	$2.95 \le V_{DDHI} \le 5.5$		250		ms
T _{EXT_HALT}	Halt Operation/Filter Halt time	2.95 ≤ V _{DDHI} ≤ 5.5		40		ms
T_{PULSE}	Pulse timing	$2.95 \le V_{DDHI} \le 5.5$	25	30	35	ms

Table 10.7 IQS128 Response Times

Power Mode	Conditions	DYCAL			
Power Mode	Conditions	Min*	Max	Unit	
Boost Power Mode ⁸	Detection	63.7	1	ms	
Doost Lowel Mode	Release	63.7	-	ms	

^{**}Minimum time calculated as causing a proximity detection on the IQS128. Prox debounce is 6 and I/O is toggled after next charge transfer cycle, requiring 7 charge cycles for the minimum time of a decision to be made.

-

⁸ IQS128 only available in Boost Power Mode. Minimum Detection and Release times = 7 x t_{CHARGE}

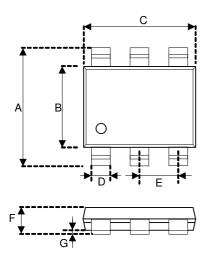




11 Packaging and Part-number Information

11.1 Packaging Information

11.1.1 TSOT23-6



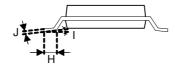


Figure 11.1 TSOT23-6 Packaging⁹

Table 11.1 TSOT23-6 Dimensions

Dimension	Min	Max	Tolerance	
Α	2.80 mm typ		Basic	
В	1.60 mm typ		Basic	
С	2.90 mm typ		Basic	
D	0.40 mm ±0.10mm			
Е	0.95 mm typ Basic			
F	1.00mm Max			
G	0.05 mm ±0.05mm			
Н	0.40 mm ±0.10mm			
	4° ±4°			
J	0.127 mm typ +0.07/-0.007			

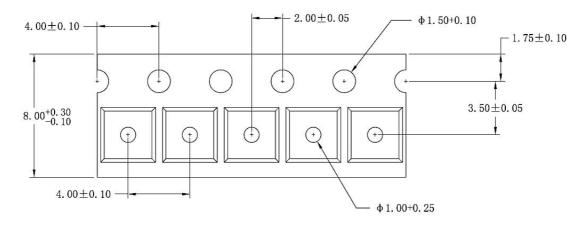
-

⁹ Drawing not on Scale





11.1.2 TSOT23-6 Tape



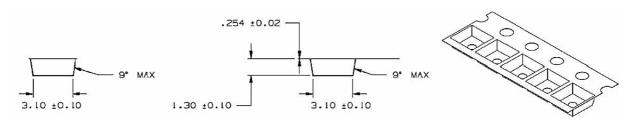
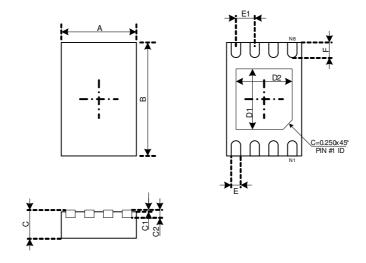


Figure 11.2 IQS128Tape Specification

11.1.3 DFN8 (2x3)



NOTE: Both Package length and width do not include mold flash and burr





Figure 11.3 DFN8 (2x3) Packaging¹⁰

Table 11.2 DFN8(2x3) Dimensions

Dimension	Min (mm) Max (mm				
Α	2.0±0.1				
В	3.0±0.1				
С	0.70 0.80				
C1	0~0.050				
C2	0.203TYP				
D1	1.60TYP				
D2	1.50	TYP			
E	0.250TYP				
E1 0.500TYP		OTYP			
F	0.400TYP				

11.1.4 DFN8 Tape

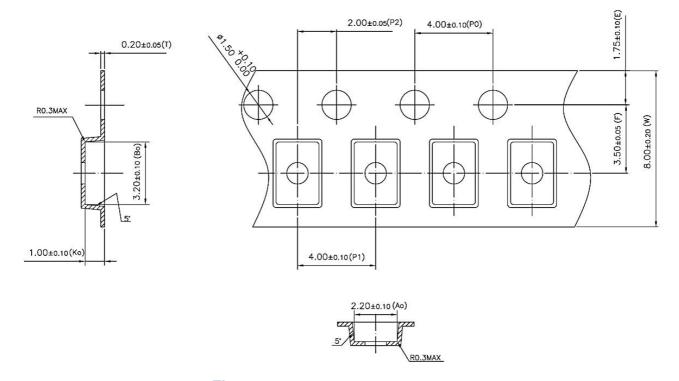


Figure 11.4 DFNTape Specification

¹⁰ Drawing not on Scale





11.1.5 Moister Sensitivity Level (MSL)

Moisture Sensitivity Level relates to the packaging and handling precautions for some semiconductors. The MSL is an electronic standard for the time period in which a moisture sensitive device can be exposed to ambient room conditions (approximately 30 °C/60%RH).

Increasingly, semiconductors have been manufactured in smaller sizes. Components such as thin fine-pitch devices and ball grid arrays could be damaged during SMT reflow when moisture trapped inside the component expands.

The expansion of trapped moisture can result in internal separation (delamination) of the plastic from the die or lead-frame, wire bond damage, die damage, and internal cracks. Most of this damage is not visible on the component surface. In extreme cases, cracks will extend to the component surface. In the most severe cases, the component will bulge and pop.

Table 11.3 IQS128 Packaging MSL Information

Package	Level (duration)				
TSOT23-6	MSL1 (unlimited at ≤30 °C/85% RH)				
DFN8 (2x3)	MSL 3 – 168 hours				

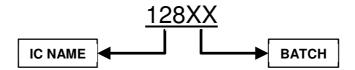




11.2 Device Packaging Convention

11.2.1 IQS128

11.2.1.1 **Top**

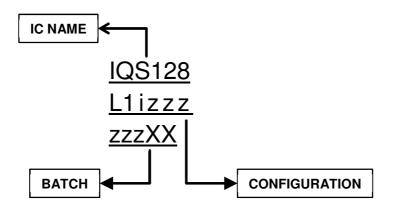


11.2.1.2 Bottom



11.2.2 IQS128L

11.2.2.1 **Top**







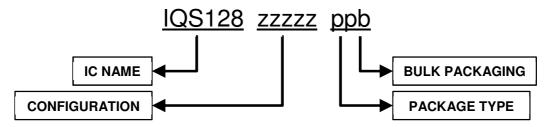
11.3 Ordering Information

Only full reels can be ordered and orders will be subject to a MOQ (Minimum Order Quantity) of a full reel. Contact the official distributor for sample quantities. A list of the distributors can be found under the "Distributors" section of www.azoteq.com.

For large orders, Azoteq can provide pre-configured devices.

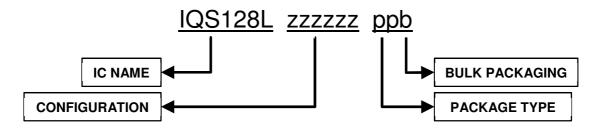
The Part-number can be generated by using USBProg.exe or the Interactive Part Number generator on the website.

11.3.1 IQS128



IC NAME	IQS128	=	IQS128
CONFIGURATION	ZZZZZ	=	IC Configuration (hexadecimal)
PACKAGE TYPE	TS	=	TSOT23-6
BULK PACKAGING	R	=	Reel (3000pcs/reel)
MOQ = 1 reel.			MOQ = 1 reel.
		N	Mass production orders shipped as full reels.

11.3.2 IQS128L



IC NAME	IQS128L	=	IQS128L
CONFIGURATION	ZZZZZZ	=	IC Configuration (hexadecimal)
PACKAGE TYPE	DN	=	DFN8 (2x3)
BULK PACKAGING	R	=	Reel (3000pcs/reel)
MOQ = 1 reel.			
		٨	Mass production orders shipped as full reels.



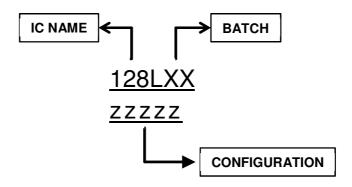


12 Errata

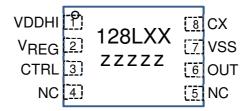
- Section 11.2.2:

It must be noted that the previous packaging for the IQS128L is still being phased out and for this reason IC's can still be found with the below packaging convention and device markings.

Packaging Convention:



Device Markings:







13 Datasheet Revision History

Version 1.10 - Preliminary Release

Version 2.0 - Added IQS128L and its functional differences

- Added ATI BASE description

Added ND feature description for IQS128

Version 2.1 - Updated aesthetics

Version 2.2 - Changed QFN to DFN

Changed Power Mode names

Version 2.3 - Updated maximum operating voltage to 5.5 throughout document

- Updated Absolute Maximum Specification: Supply voltage to 6.5V.

(Only intended for OTP programming!)

Version 2.4 - Updated POR and BOR table

- Updated packaging and part-number information

- Changed Current Sample references to Counts (CS)

- Changed Antenna references to Electrode

- Changed Auto-ATI references to ATI

Changed Device Markings

- Added Tape/Reel Specification

- Moved Section On Packaging Information to Section 12

- Made Revision History a section on its own

Added Tape Specification

Added Errata to accommodate previous packaging

Version 2.5 - Fixed TSOT23-6 Package dimension information





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The following patents relate to the device or usage of the device: US 6,249,089 B1, US 6,621,225 B2, US 6,650,066 B2, US 6,952,084 B2, US 6,984,900 B1, US 7,084,526 B2, US 7,084,531 B2, US 7,119,459 B2, US 7,265,494 B2, US 7,291,940 B2, US 7,329,970 B2, US 7,336,037 B2, US 7,443,101 B2, US 7,466,040 B2, US 7,498,749 B2, US 7,528,508 B2, US 7,755,219 B2, US 7,772,781, US 7,781,980 B2, US 7,915,765 B2, EP 1 120 018 B1, EP 1 206 168 B1, EP 1 308 913 B1, EP 1 530 178 B1, ZL 99 8 14357.X, AUS 761094

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